Lighting ColorYellow Green

## LNJ318C8TRA

### Surface Mounting Chip LED

Dome-Lens Type

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

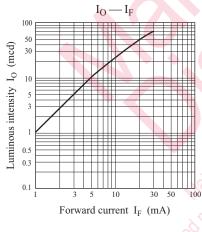
Parameter	Symbol	Symbol Rating			
Power dissipation	$P_{\mathrm{D}}$	60	mW		
Forward current	$I_{\mathrm{F}}$	20	mA		
Pulse forward current *	$I_{FP}$	60	mA		
Reverse voltage	V <sub>R</sub>	4	V		
Operating ambient temperature	T <sub>opr</sub>	-30 to +85	°C		
Storage temperature	T <sub>stg</sub>	-40 to +100	°C		

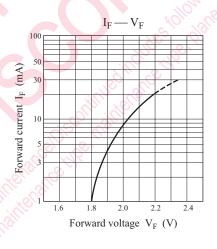
Note) \*: The condition of I<sub>FP</sub> is duty 10%, Pulse width 1 msec.

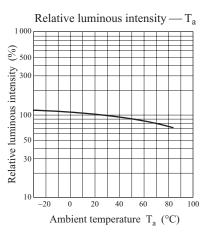
#### ■ Electro-Optical Characteristics $T_a = 25$ °C±3°C

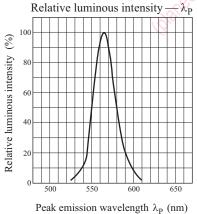
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *	I <sub>O</sub>	$I_F = 10 \text{ mA}$	10	25	.CO	mcd
Reverse current	$I_R$	$V_R = 4 V$	J. Ill	30,0	10	μΑ
Forward voltage	$V_{\rm F}$	$I_F = 10 \text{ mA}$	9110	2.03	2.60	V
Peak emission wavelength	$\lambda_{ m P}$	$I_F = 10 \text{ mA}$	" IN THE	565		nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$	OUL	30		nm

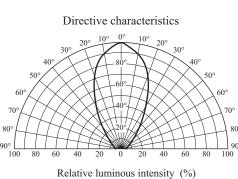
Note) \*: Measurement tolerance: ±20%

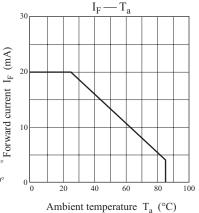






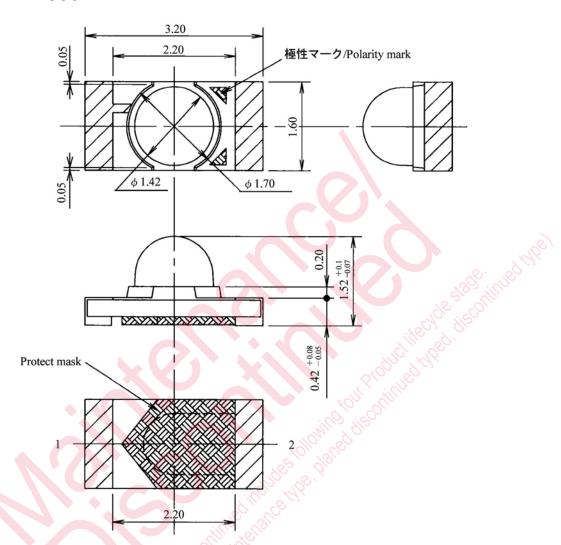






### ■ Package (Unit: mm)

## KLTLTN2K1800



- Pin name
  - 1: Anode
  - 2: Cathode

2 SHD00648BEK

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